### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Chia-Chung Wang et al.

Assignee:

Bridge Semiconductor Corporation

Title:

METHOD OF MAKING A SEMICONDUCTOR CHIP

ASSEMBLY WITH A CONDUCTIVE TRACE AND A

SUBSTRATE

Serial No.:

Unknown

Filed:

Herewith

Examiner:

Unknown

Group Art Unit:

Unknown

Atty. Docket No.:

**BDG018** 

COMMISSIONER FOR PATENTS

P.O. Box 1450

Alexandria, VA 22313-1450

#### **POWER OF ATTORNEY**

Bridge Semiconductor Corporation, as assignee of the entire interest in the aboveidentified application, hereby appoints the following attorney to prosecute this application and to transact all business in the United States Patent and Trademark Office in connection therewith.

David M. Sigmond Reg. No. 34,013

Attached to this power is a Statement Under 37 C.F.R. § 3.73(b) Establishing Right of Assignee to Take Action.

Charles W.C. Lin

Chief Executive Officer

Bridge Semiconductor Corporation

Date: 19, 2003

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## STATEMENT CLAIMING SMALL ENTITY STATUS BY SMALL BUSINESS CONCERN

I hereby state that I am an official of the small business concern empowered to act on behalf of the concern identified below:

Bridge Semiconductor Corporation 3<sup>rd</sup> Floor, 157 Li-Te Road Peitou District Taipei, Taiwan 112

I hereby state that the above-identified small business concern qualifies as a small business concern, as defined in 13 C.F.R. § 121.12, and reproduced in 37 C.F.R. § 1.9(d), for purposes of paying reduced fees to the United States Patent and Trademark Office under Sections 41(a) and 41(b) of Title 35 of the United States Code in that the number of employees of the concern, including those of its affiliates, does not exceed 500 persons. For purposes of this Statement, (1) the number of employees of the business concern is the average over the previous fiscal year of the concern of the persons employed on a full-time, part-time or temporary basis during each of the pay periods of the fiscal year, and (2) concerns are affiliates of each other

when either, directly or indirectly, one concern controls or has the power to control the other, or a third party controls or has the power to control both.

I hereby state that rights under contract or law have been conveyed to, and remain with, the small business concern identified above with regard to the invention described in the specification filed herewith with the title as listed above.

If the rights held by the above-identified small business concern are not exclusive, each individual, concern or organization having rights in the invention is listed below and no rights to the invention are held by any person, other than the inventor, who would not qualify as an independent inventor under 37 C.F.R. § 1.9(c) if that person had made the invention, or by any concern that would not qualify as a small business concern under 37 C.F.R. § 1.9(d), or a nonprofit organization under 37 C.F.R. § 1.9(e).

Each such person, concern, or organization having any rights in the invention is listed below:

> No such person, concern or organization exists.

I acknowledge that separate statements are required from each named person, concern or organization having rights to the invention stating their status as small entities in accordance with 37 C.F.R. § 1.27.

I acknowledge the duty to file, in this application or patent, notification or any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate in accordance with 37 C.F.R. § 1.28(b).

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application, any patent issued thereon, or any patent to which this verified statement is directed.

Charles W.C. Lin Chief Executive Officer Bridge Semiconductor Corporation 3<sup>rd</sup> Floor, 157 Li-Te Road

Peitou District

Taipei, Taiwan 112

# DECLARATION FOR PATENT APPLICATION IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe that, I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH A CONDUCTIVE TRACE AND A SUBSTRATE, the specification of which is identified as Attorney Docket No. BDG018 and attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to patentability in accordance with 37 C.F.R. §§ 1.56(a)-(b) as set forth on the attached sheet at Page 3 hereof and which I have read.

I hereby claim foreign priority benefits under 35 U.S.C. §§ 119(a)-(d) or 365(a)-(b) of any foreign application(s) for patent or inventor's certificate(s) or PCT international application(s) which designate at least one country other than the United States of America, listed below and have also identified below any foreign application(s) for patent or inventor's certificate(s) or PCT international application(s) having a filing date before that of the application(s) on which priority is claimed:

Prior Foreign	Priority Claimed		
<u>Number</u>	<b>Country</b>	Month/Day/Year Filed	Yes No
N/A		•	<del></del>

I hereby claim the benefit under 35 U.S.C. §§ 120 and 365(c) of any United States application(s) and any PCT international application(s) designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in such prior application(s) in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information material to patentability in accordance with 37 CFR §§ 1.56(a)-(b) which occurred between the filing date(s) of the prior application(s) and the national or PCT international filing date of this application:

Filing Date	Status: patented, pending, abandoned
September 24, 2001	Pending
June 11, 2001	Pending
October 13, 2000	Patented
	September 24, 2001 June 11, 2001

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

Application Serial No. Filing Date
N/A

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

1)	Inventor's Signature	mg Wars Date
	Inventor's Name (typed):	Chia-Chung Wang
	Citizenship:	Taiwan
	Residence:	3 <sup>rd</sup> Floor, #12, Alley 33, Section 2, Jungshing Road Judung Jen Hsinchu, Taiwan 310
	Post Office Address:	Same as Residence
2)	Inventor's Signature	Date Aug. 19, 2003
	Inventor's Name (typed):	Charles W.C. Lin
	Citizenship:	United States
	Residence:	34 Pinewood Grove Singapore 738290
	Post Office Address:	Same as Residence